

AP15P10GH-VB Datasheet P-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)			
- 100	0.250 at $V_{GS} = -10 \text{ V}$	- 8.8	11.7			
- 100	0.280 at V _{GS} = - 4.5 V	- 8.0	11.7			

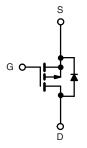
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested
 Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

- Power Switch
- DC/DC Converters



P-Channel MOSFET

TO-252	
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0	
	Drain Connected to Tab
G D S	
Top View	

ABSOLUTE MAXIMUM RATINGS T _C = 25 °C, unless otherwise noted						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V _{DS}	- 100	V			
Gate-Source Voltage		V _{GS}	± 20	V		
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 25 °C	L	- 8.8			
Continuous Diam Current (1) = 150 °C)	T _C = 70 °C	- I _D	- 7.1			
Pulsed Drain Current	I _{DM}	- 25	Α			
Avalanche Current		I _{AS}	- 18			
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	16.2	mJ		
M	T _C = 25 °C	В	32.1 ^b	w		
Maximum Power Dissipation ^a	T _A = 25 °C ^c	- P _D	2.5			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	50	°C/W		
Junction-to-Case (Drain)	R _{thJC}	3.9	C/VV		

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

服务热线:400-655-8788

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS}$ $V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$				V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 2.5	٧	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
		V _{DS} = - 100 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 100 V, V _{GS} = 0 V, T _J = 125 °C			- 50	μΑ	
		V _{DS} = - 100 V, V _{GS} = 0 V, T _J = 150 °C			- 250	1	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 15			Α	
	Ь	V _{GS} = - 10 V, I _D = - 3.6 A		0.250		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 3.4 A		0.280			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 3.6 A		12		S	
Dynamic ^b				•			
Input Capacitance	C _{iss}			1055		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = - 50 V, f = 1 MHz		65			
Reverse Transfer Capacitance	C _{rss}	1		41			
		V _{DS} = - 50 V, V _{GS} = - 10 V, I _D = - 3.6 A		23.2	34.8		
Total Gate Charge ^c	Qg			11.7	17.6		
Gate-Source Charge ^c	$Q_{gs}$	$V_{DS} = -50 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -3.6 \text{ A}$		3.5		nC	
Gate-Drain Charge ^c	$Q_{gd}$			4.8			
Gate Resistance	$R_g$	f = 1 MHz	1.2	5.7	11.5	Ω	
Turn-On Delay Time ^c	t _{d(on)}			7	14		
Rise Time ^c	t _r	$V_{DD} = -50 \text{ V}, R_L = 17.2 \Omega$		12	18		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ - 2.9 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		33	50	ns	
Fall Time ^c	t _f	1		9	18		
Drain-Source Body Diode Ratings ar	nd Characteri	stics T _C = 25 °C ^b					
Continuous Current	I _S	Is			- 8.8		
Pulsed Current	I _{SM}				- 15	15 A	
Forward Voltage ^a	V _{SD}	I _F = - 2.9 A, V _{GS} = 0 V		- 0.8	- 1.5	V	
Reverse Recovery Time	t _{rr}			50	75	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 2.9 A, dl/dt = 100 A/μs		- 4	- 6	Α	
Reverse Recovery Charge	Q _{rr}	† †		98	147	nC	

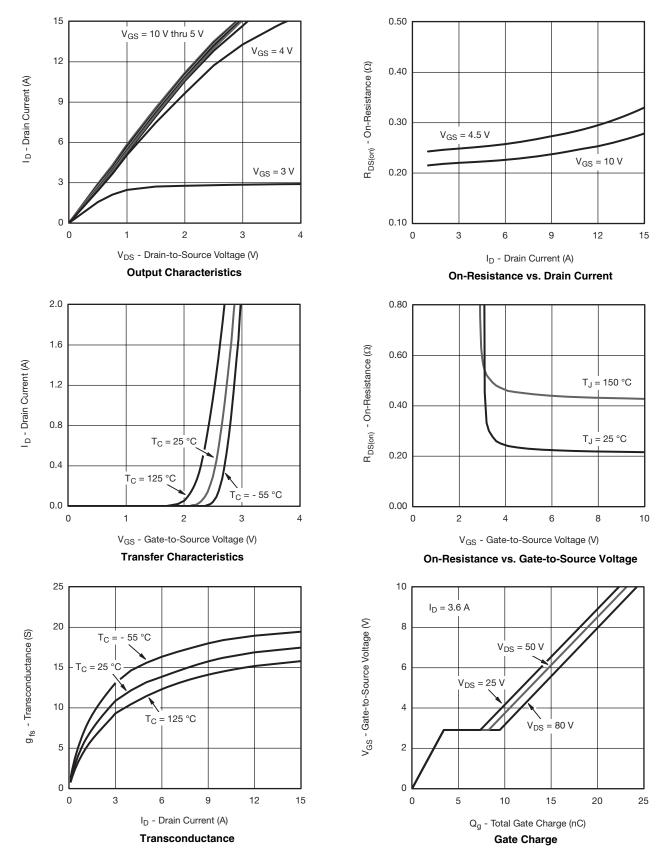
#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

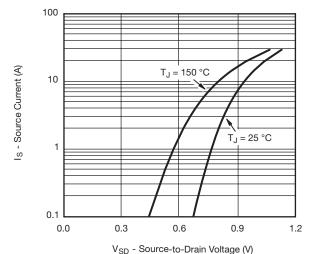


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

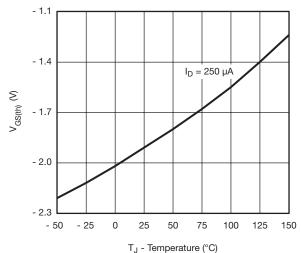




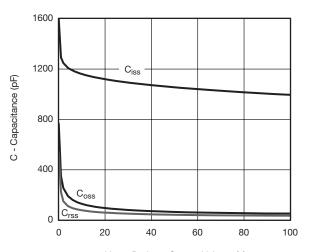
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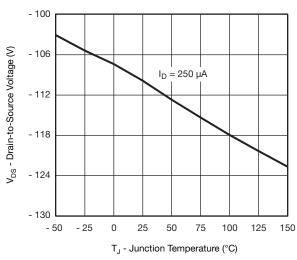
Source-Drain Diode Forward Voltage



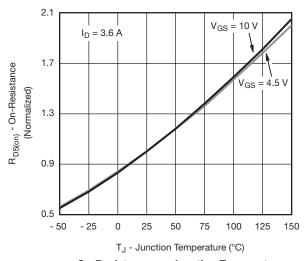
Threshold Voltage



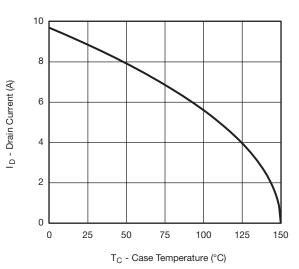
 $V_{DS}$  - Drain-to-Source Voltage (V)  $\label{eq:capacitance}$ 



**Drain Source Breakdown vs. Junction Temperature** 



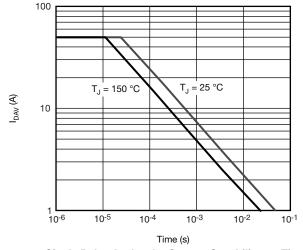
On-Resistance vs. Junction Temperature

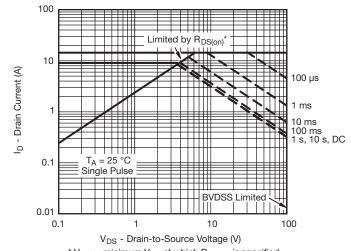


**Current Derating** 



## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



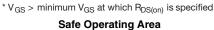


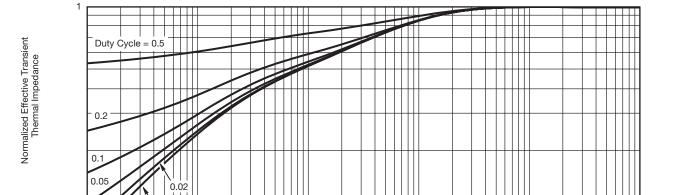
Single Pulse Avalanche Current Capability vs. Time

Single Pulse

10-3

0.1 L 10⁻⁴





10⁻²

Square Wave Pulse Duration (s)

Normalized Thermal Transient Impedance, Junction-to-Case

10-1

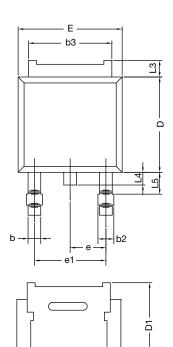
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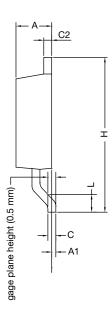
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## **TO-252AA Case Outline**





	MILLIN	MILLIMETERS		HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	2.18	2.38	0.086	0.094
A1	-	0.127	-	0.005
b	0.64	0.88	0.025	0.035
b2	0.76	1.14	0.030	0.045
b3	4.95	5.46	0.195	0.215
С	0.46	0.61	0.018	0.024
C2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	4.10	-	0.161	-
E	6.35	6.73	0.250	0.265
E1	4.32	-	0.170	-
Н	9.40	10.41	0.370	0.410
е	2.28	BSC	0.090	BSC
e1	4.56 BSC		0.180 BSC	
L	1.40	1.78	0.055	0.070
L3	0.89	1.27	0.035	0.050
L4	-	1.02	-	0.040
L5	1.01	1.52	0.040	0.060
ECN: T16-0236-Rev. P, 16-May-16				

ECN: T16-0 DWG: 5347

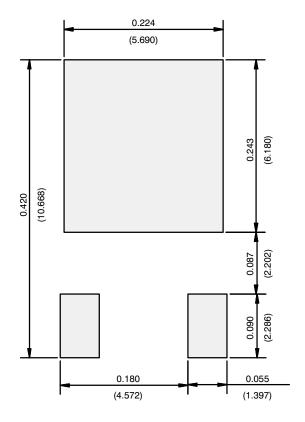
#### Notes

• Dimension L3 is for reference only.



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### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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